FINAL CALL FOR PAPERS

ASQED 2013
5th Asia Symposium on
QUALITY ELECTRONIC DESIGN

Aug. 26-28, 2013 - Penang, Malaysia

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Symposium 2013
www.asqed.com

IEEE
CPMT
IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY
CAS
ReliabilitySociety
IPC

ASQED 2013 is organized by the International Society for Quality Electronic Design, and is financially sponsored and managed by SHRDC. Symposium gathers leading industrial and educational organizations and it is aimed at bridging the gap among electronic/semiconductor ecosystem members providing electronic design tools and processes, integrated circuit technologies, processes & manufacturing, to achieve design quality. The conference emphasizes innovations and the latest developments in IC and system Design, EDA, Semiconductor Process Technology, IC Packaging, Test, and Manufacturing. ASQED spans two days, in three parallel tracks, hosting over 60 technical presentations, several keynote speakers, tutorials, exhibits and other informal meetings. Past conference proceedings will be published by IEEE and posted in the digital library. ASQED 2013 hosts the 2nd **Microelectronic Olympiad** competition in Malaysia. Refer to the conference website for details.

Papers and tutorial proposals are requested in the following areas

As a premier international conference, ASQED 2013 accepts and promotes papers in following topics:

IC and System-level Design & Test System-level Design, Methodologies & Tools
- *Analog, Digital, Mixed-Signal and RFIC Design*
- *FPGA Architecture, Design, and CAD*
- *Robust & Power-conscious Circuits & Systems*
- *Design of Reliable & Fault Tolerant Circuits and Systems*
- *Design of Embedded Systems*

IP Design, Quality, Interoperability and Reuse
- *Design Verification and Design for Testability*
- *Physical Design, Methodologies & Tools*
- *EDA Methodologies, Tools, Flows*

Semiconductor Process and Devices Emerging/Innovative
- *Process & Device Technologies*
- *Yield and Reliability Analysis, Prediction, and Management*

Advanced IC Packaging, 3D ICs IC Package - Design Interactions & Co-Design
- *Advanced 3D ICs & 3D Packaging*
- *High density PCB/PWB*
- *Signal and Power Integrity*

Sensors Technology, Design and Applications, MEMS/NEMS

Submission of Papers

Paper submission must be done on-line through the conference web site. The guidelines for the final paper format are provided on the symposium website. Authors should submit FULL-LENGTH, original, unpublished papers (Minimum 4, maximum 10 pages) along with abstract of about 200 words. Please check the as-printed appearance of your paper before sending your paper. In case of any problems, email asqed2013@asqed.com. Please note the following important dates:

isQED
www.ISQED.com

Paper Submission Deadline	**May 17, 2013**
Acceptance Notifications	**June 14, 2013**
Final Camera-Ready paper	**July 19, 2013**

Extended

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